

1 39808/PAN/C715

USE OF CHIP-ON-BOARD TECHNOLOGY TO MOUNT OPTICAL TRANSMITTING
AND DETECTING DEVICES WITH A PROTECTIVE COVERING WITH MULTIPLE
5 OPTICAL INTERFACE OPTIONS

ABSTRACT OF THE DISCLOSURE

A packaging system for optoelectronic devices that does not
require the optoelectronic device to be hermetically sealed,
10 whereby the optoelectronic device is mounted directly on a
substrate, allowing for high-speed trace designs up to the die
for excellent high speed signal integrity and EMI performance.

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DLF PAS264190.3--9/29/00 1:26 PM

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